



Material Content Data Sheet



Sales Product Name	BTS723GW			Issued		29. August 2013		
MA#	MA000990168							
Package	PG-DSO-14-37			Weight*		144.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.803	4.02	4.02	40191	40191
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		104	
	non noble metal	zinc	7440-66-6	0.060	0.04		418	
	non noble metal	iron	7439-89-6	1.207	0.84		8359	
	non noble metal	copper	7440-50-8	49.007	33.94	34.83	339423	348304
wire	noble metal	gold	7440-57-5	1.105	0.77	0.77	7651	7651
encapsulation	organic material	carbon black	1333-86-4	0.167	0.12		1156	
	plastics	epoxy resin	-	7.675	5.32		53159	
	inorganic material	silicondioxide	60676-86-0	75.585	52.34	57.78	523504	577819
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8492	8492
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7132	7132
glue	plastics	epoxy resin	-	0.263	0.18		1822	
	noble metal	silver	7440-22-4	1.240	0.86	1.04	8589	10411
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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